

#### **Features**

- Leadless chip carrier package is hermetically sealed for superior aging and field performance
- Crystal angle controlled to ±0.5 minute for excellent temperature stability
- 168 hour Class B burn-in and extensive environmental testing for best performance in rugged field environments
- Guarantee start-up with a ramping DC supply
- Start-up time <5ms, typical
- Tristate option available
- Calculated MTBF is 3.8x10<sup>6</sup> hours at 125°C



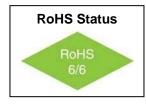
These high reliability oscillators provide HCMOS clock waveforms for applications subjected to the most stringent environmental conditions. They are mechanically robust and weigh less than 0.2 grams. This 5x7 mm SMD package has a hermetic seal, thus ensuring the integrity of each oscillator. Each oscillator is burned-in at 125°C for 168 hours, temperature cycled and centrifuged then fully tested in accordance with Table 1. Reliability tests are performed per Table 2. The calculated MTBF is 3.8x10<sup>6</sup> at 125°C.

Parameter	Symbol	Condition	Min	Тур	Max	Unit	Note
Frequency Range	F		0.85		165	MHz	
Frequency Stability	ΔF/F	Vs. Operating Temperature ±25			±75	nnm	See Chart
		Aging 1 <sup>st</sup> Year After 1 <sup>st</sup> Year			±3 ±1	ppm	
Operating Temperature Range	т		-55°		+125°	°C	See Chart
Input Voltage	Vcc		1.7	1.8	1.9	V	
Input Current	lcc	850 KHz to 70 MHz, with 15pF load 70.1 to 165.0 MHz with 15pF load		7.0 15.0	10.0 18.0	mA	
Jitter RMS					10	ps	
Waveform Symmetry		Measured at 50% V <sub>DD</sub> 850 KHz to 70 MHz 70.1 to 165.0 MHz		48/52 45/55	45/55 40/60	%	
Rise / Fall Time	Tr/Tf				5	ns	
Output Level		"Zero" Level "One" Level	90% V <sub>DD</sub>		$10\% V_{DD}$	V	
Input Requirements for Pin 1		"1": On-Pin 1 may float or 90% $V_{DD}$ min. "0": Tristate-Pin 1 requires 10% $V_{DD}$					

#### **Electrical Specifications**









#### **Environmental and Mechanical Conditions**

Parameter	Condition				
Storage Temperature	-55°C to +150°C				
Shock	1000 Gs, 0.35 ms, $\frac{1}{2}$ sine wave, 3 shocks in each plane				
Vibration	10-2000 Hz of 0.06" d.a. or 20Gs, whichever is less				
Humidity	Resistant to 85° R.H. at 85°C				
Leak	Per MIL-STD-883, Method 1014, Cond. A1 and Cond. C				
Case	Hermetically sealed ceramic LCC				
Pads	15 microinch of gold over nickel				
Resistance to Solvents	Per MIL-STD-202, Method 215				
Marking	Epoxy ink or laser engraved				

FIXED OUTPUT	TRISTATE	Oneneting	Frequency Stability	
Model	Model	Operating Temperature		
VFH2321	VFH2421	-55°C to +85°C	±25 ppm	
VFH2322	VFH2422	-55°C to +85°C	±50 ppm	
VFH2323	VFH2423	-55°C to +125°C	±75 ppm	
VFH2324	VFH2424	-55°C to +125°C	±50 ppm	

#### Table 1 Each unit undergoes the following: 1. Stabilization Bake MIL-STD-883 Method 1008, Cond, B 2. Temperature Cycling MIL-STD-883 Method 1010, Cond, B 3. Constant Acceleration MIL-STD-883 Method 2001, Cond, A 4. Burn-in MIL-STD-883 Method 1015, Cond B (125°C for 168 hours with bias) 5. Fine Leak MIL-STD-883 Method 1014, Cond. A1 6. Gross Leak MIL-STD-883 Method 1014, Cond C 7. Electrical Test at 25°C and temperature extremes, as follows: A. Frequency F. Duty Cycle B. Current G. Frequency at max V<sub>DD</sub> C. Rise Time H. Frequency at min $V_{DD}$ D. Fall Time I. "Zero" logic level J. Tristate E. Duty Cycle

Test Data on each unit is available for additional cost

### **Thermal Characteristics**

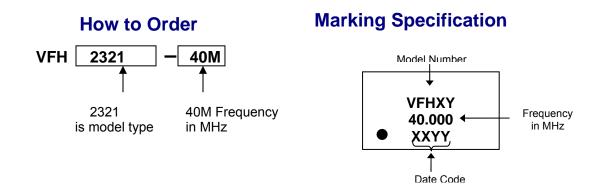
Thermal Resistance From Junction to Case, RØjc 16 °C/Watt

#### **Surface Mount Application**

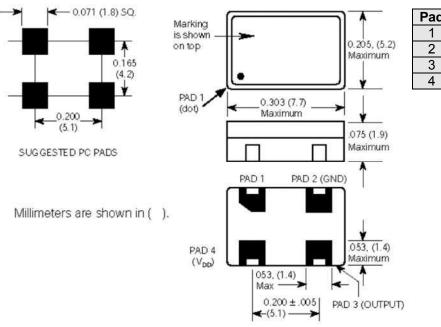
These packages are designed for reflow soldering in accordance with recommended profiles. For hand-soldering, the temperature of the iron should not exceed 400°C for three seconds.





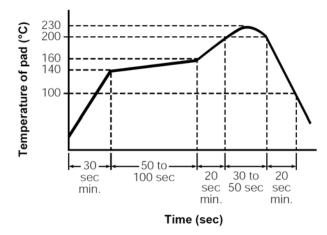


### Package

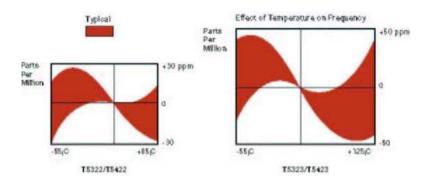


Pad	VFH2321-VFH2324	VFH2421-VFH2424		
1	N/C	Tristate		
2	Ground			
3	Output			
4	V	D		

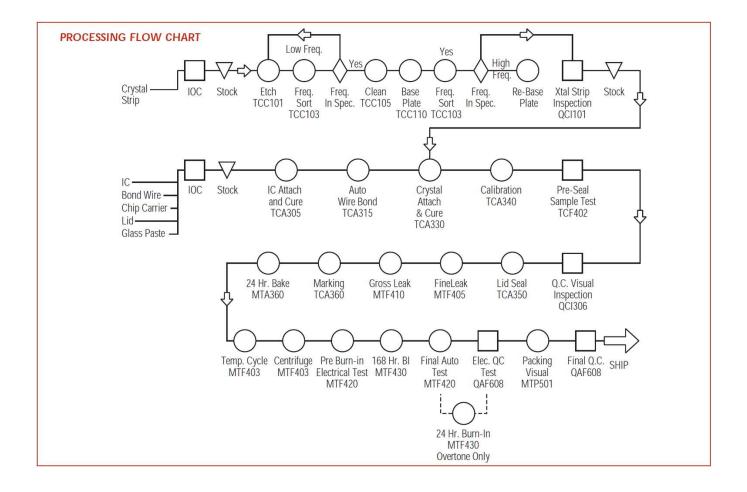




**Recommended Reflow Soldering Profile** 









# TABLE 2 Reliability Test Procedures and Conditions for Quartz Crystal Oscillators

1. Group A				В.	Subgroup 2-4 pcs (One-half of Subgroup 1)			
Electrical Characteristics at -55°C, and 125°C (85°C for VFH2321, VFH2421, VFH2322, VFH2422) Frequency @ 1.7, 1.8, and 1.9 volts Symmetry (Duty Cycle) Input current Zero/One levels				<u>Standard</u> MIL-STD-883	Condition Method 1011 COND. B	<u>Descriptio</u> n Thermal Shock Liq. To liq. -55°C to 125°C, 15 cycles	End point Measurement Frequency Output waveform	
Rise/Fall times Physical Dimensions Length/width				MIL-STD-202	Method 105 COND. B	Altitude, 3.44 inch Hg. 12 hrs	Frequency Output waveform	
Height Seal (Visual) Package finish (Corrosion, discoloration, etc.) Marking placement/legibility				MIL-STD-883	Method 1004	Moisture resist. with 1.8V applied 25°C to 65°C, 90 to 100% RH, 10 cycles	Frequency Output waveform	
<ol> <li>Group B- Life Test 1000 hrs at or above 125°C, 1.8V VDC, with proper load</li> <li>Group C- All units have passed Group A testing A. Subgroup 1-8 pcs.</li> </ol>			MIL-STD-202	Method 210 COND.A	Resistance to Solder Heat Immersion @350°C 3.5 sec	Frequency Output waveform		
Standard Con	ndition Description		End Point Measurement Frequency Output waveform Frequency	C. Subgroups 3-4 pcs. (One half of Subgroup 1)				
CON	MIL-STD-883 Method 2002 Mechanical Shock F COND.B 1500 g's, 0.5ms O 5 drops, 6 axis	Standard		<u>Condition</u> Storage Temp. No. Oper	<u>Description</u> 24 hrs. @ -55°C 24 hrs. @ 125°C	End point Measurement Frequency Output waveform		
	ND. A.	······································	Output waveform	MIL-STD-883	Method 1009 COND. A	Salt Atmosphere 24 hrs. @ 35°C 0.5-3.0% Solution	Frequency Output waveform Visual	
MIL-STD-883 Meth	hod 2003	Solderability	Visual 95% Coverage	MIL-STD-883	Method 1014 COND, A1	Fine Leak	Qs <5 X10⁻ <sup>8</sup>	
				MIL-STD-883	Method 1014 COND. C1	Gross Leak	Visual in 125°C Detector fluid	

